EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	971	"257"/$.ccls. and (substrate wafer carrier board) with first with (bump ball) same (chip ic die) and reflow$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/23 14:11
L2	333	l1 and flux	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/23 14:09
L3	4383	"257"/$.ccls. and (substrate wafer carrier board) same (bump ball) same (chip ic die) and reflow$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/23 14:18
L4	1315	l3 and flux	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/23 14:11
L5	521	l4 and (bump ball) with (tin Sn)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/23 14:12
L6	209	l5 and pin	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/23 14:12
L7	1887	"438"/$.ccls. and (substrate wafer carrier board) same (bump ball) same (chip ic die) and reflow$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/23 14:20
L8	615	l7 and flux	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/23 15:02